



Material Content Data Sheet



Sales Product Name				IPP70N04S3-07		Issued		25. September 2017	
MA#				MA000366362					
Package				PG-TO220-3-1		Weight*		2034.71 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.588	0.13	0.13	1272	1272	
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
	non noble metal	iron	7439-89-6	0.816	0.04		401		
wire	non noble metal	copper	7440-50-8	815.335	40.08	40.13	400712	401233	
	non noble metal	aluminium	7429-90-5	6.271	0.31	0.31	3082	3082	
encapsulation	organic material	carbon black	1333-86-4	8.926	0.44		4387		
	plastics	epoxy resin	-	98.187	4.83		48256		
leadfinish	inorganic material	silicondioxide	60676-86-0	487.959	23.98	29.25	239818	292461	
	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10548	10548	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121	
solder	non noble metal	tin	7440-31-5	0.049	0.00		24		
	noble metal	silver	7440-22-4	0.061	0.00		30		
heatspreader	non noble metal	lead	7439-92-1	2.333	0.11	0.11	1147	1201	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
*deviation	non noble metal	iron	7439-89-6	0.590	0.03		290		
	non noble metal	copper	7440-50-8	589.466	28.97	29.01	289705	290082	
						Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com